

Description

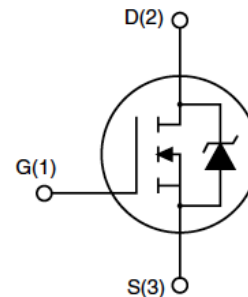
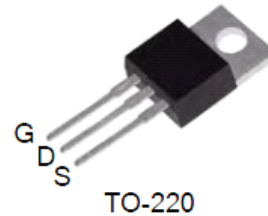
Features

V_{DSS}	$R_{DS(ON)}$ @ 10V (typ)	I_D
55V	6.8m Ω	110A

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

Application

- UPS
- High efficiency switch mode power supplies



Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter		Max.	Units
			TO-220	
V_{DSS}	Drain-Source Voltage		55	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	110 ^{note5}	A
		$T_C = 100^\circ\text{C}$	80	A
I_{DM}	Pulsed Drain Current ^{note1}		390	A
I_{AR}	Avalanche Current ^{note1}		60	A
E_{AR}	Repetitive Avalanche Energy ^{note1}		20	mJ
dv/dt	Peak Diode Recovery Energy ^{note3}		5.0	V/ns
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	200	W
	Linear Derating Factor	$T_C > 25^\circ\text{C}$	1.3	W/ $^\circ\text{C}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.75	$^\circ\text{C/W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	$^\circ\text{C}$

*Drain current limited by maximum junction temperature

Electrical Characteristics $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	55	-	-	V
$\Delta V_{(BR)DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	Reference to 25°C , $I_D = 250\mu A$	-	0.057	-	$V/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 55V, V_{GS} = 0V$	-	-	1	μA
		$V_{DS} = 44V, T_C = 125^\circ\text{C}$	-	-	10	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage ^{note4}	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	-	4	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 60A$	-	6.8	8.0	m Ω
g_{FS}	Forward Transconductance	$V_{DS} = 20V, I_D = 60A$	45	-	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$ $f = 1.0\text{MHz}$	-	3291	-	pF
C_{oss}	Output Capacitance		-	671.5	-	pF
C_{rss}	Reverse Transfer Capacitance		-	112.1	-	pF
Q_g	Total Gate Charge	$V_{DD} = 44V, I_D = 60A,$ $V_{GS} = 10V$	-	112	-	nC
Q_{gs}	Gate-Source Charge		-	23.2	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	34.9	-	nC
EAS	Single Pulse Avalanche Energy ^{note2}	$I_{AS} = 20A, L = 5\text{mH}$	-	1000 ^{note6}	267 ^{note7}	mJ
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 28V, I_D = 60A,$ $R_G = 5\Omega, V_{GS} = 10V$	-	19.5	-	ns
t_r	Turn-On Rise Time		-	50.7	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	55	-	ns
t_f	Turn-Off Fall Time		-	24.6	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	110	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	390	-	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_S = 60A$	-	-	1.3	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0V, I_F = 60A,$ $di/dt = 100A/\mu s$	-	62.3	-	ns
Q_{rr}	Reverse Recovery Charge		-	137	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $L = 5\text{mH}, I_{AS} = 20A, V_{DD} = 50V, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 60A, di/dt \leq 200A/\mu s, V_{DD} \leq B_{VDSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.
5. Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 75A.
6. This is a typical value at device destruction and represents operation outside rated limits.
7. This is a calculated value limited to $T_J = 175^\circ\text{C}$.

Typical Performance Characteristics

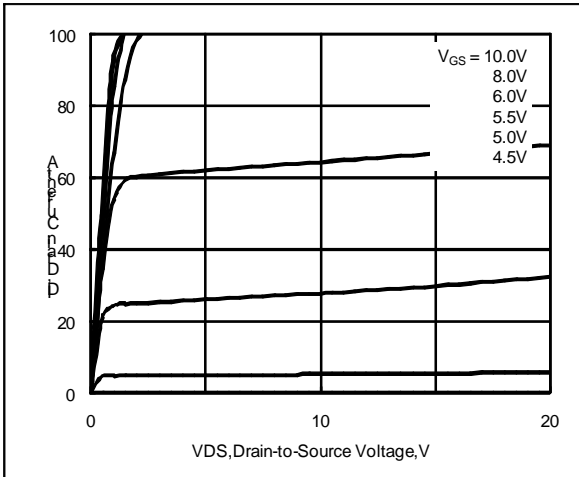


Figure 1. Output Characteristics

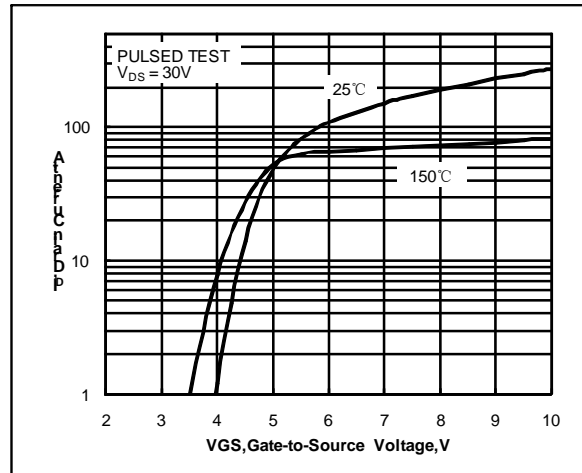


Figure 2. Transfer Characteristics

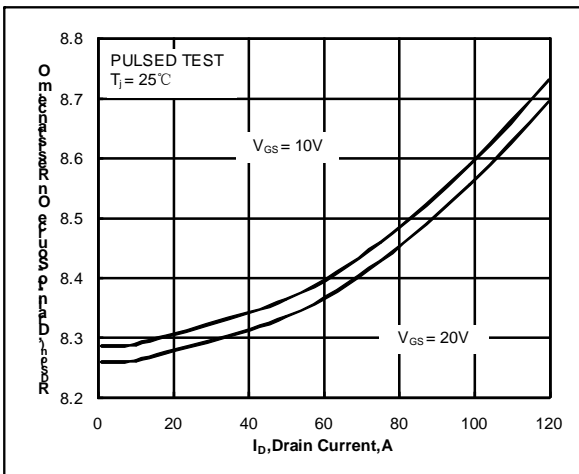


Figure 3. Drain-to-Source On Resistance vs. Drain Current and Gate Voltage

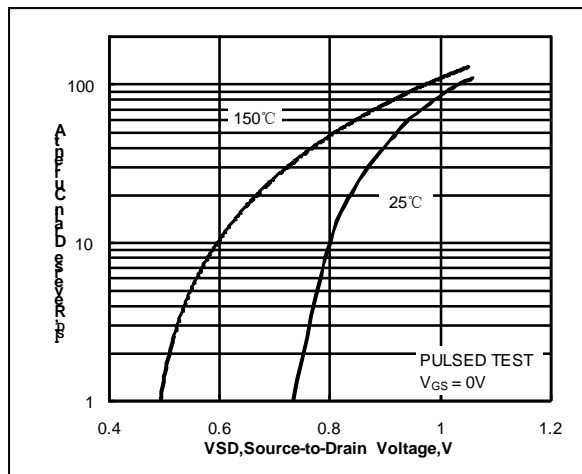


Figure 4. Body Diode Forward Voltage vs. Source Current and Temperature

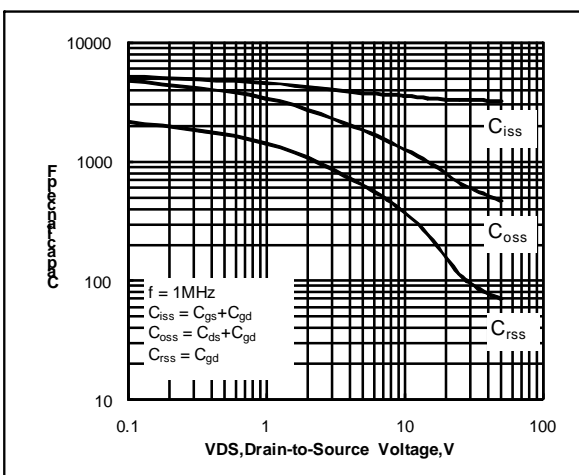


Figure 5. Capacitance Characteristics

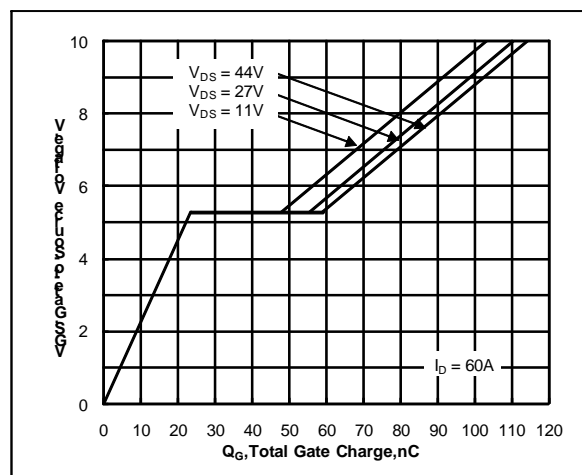


Figure 6. Gate Charge Characteristics

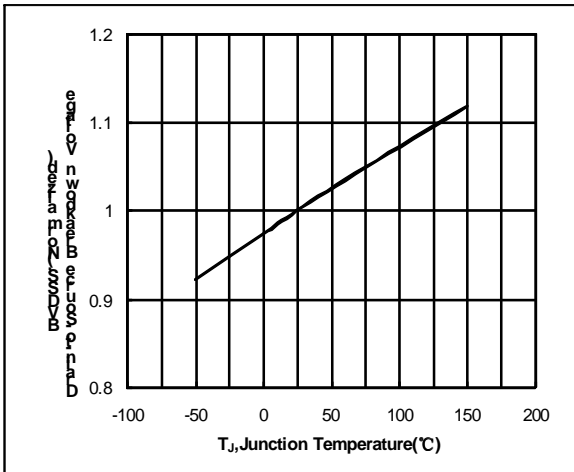


Figure 7. Normalized Breakdown Voltage vs. Junction Temperature

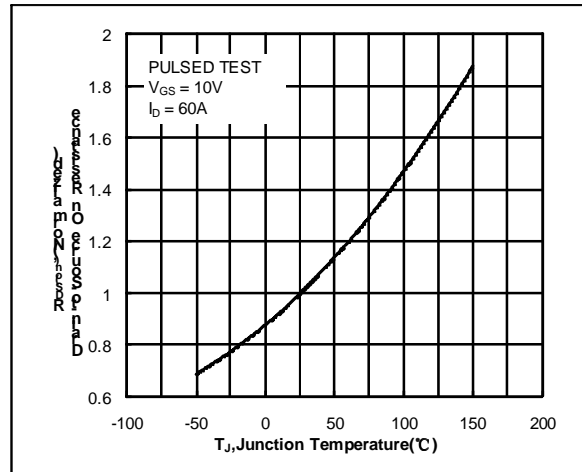


Figure 8. Normalized On Resistance vs. Junction Temperature

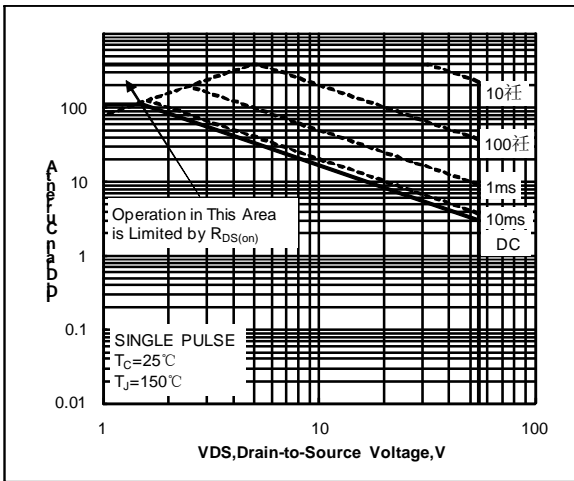


Figure 9. Maximum Safe Operating Area for OP3205B

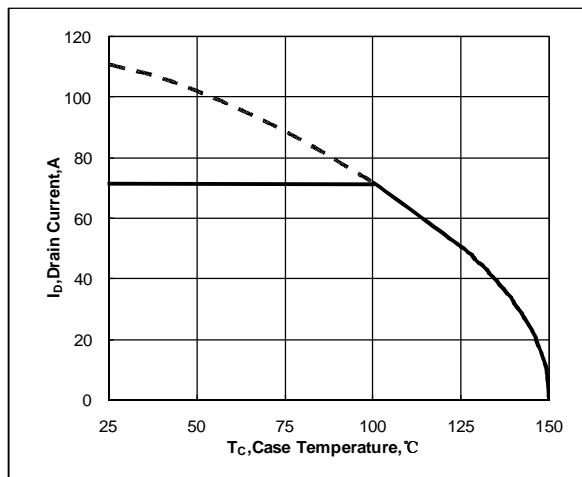


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

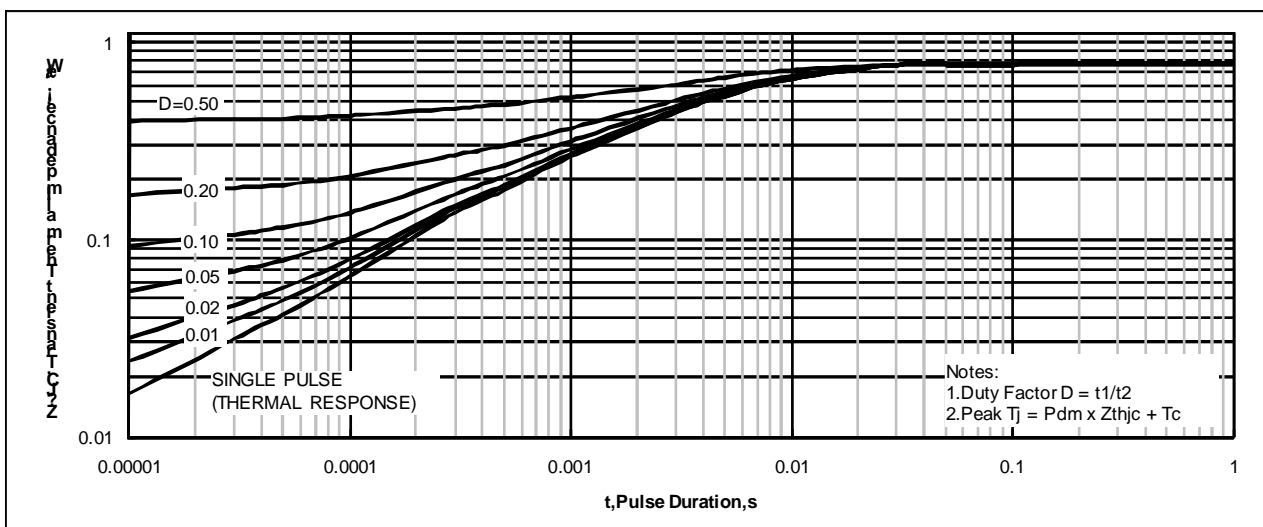


Figure 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case for OP3205B

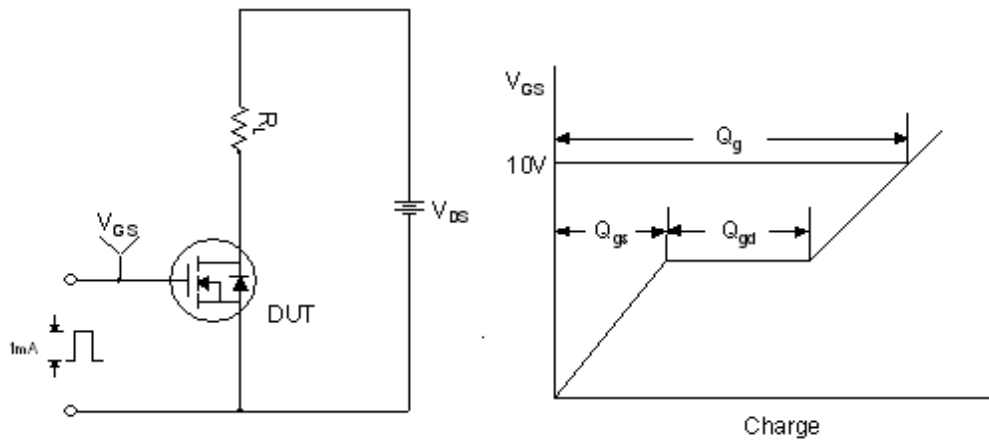


Figure 12. Gate Charge Test Circuit & Waveform

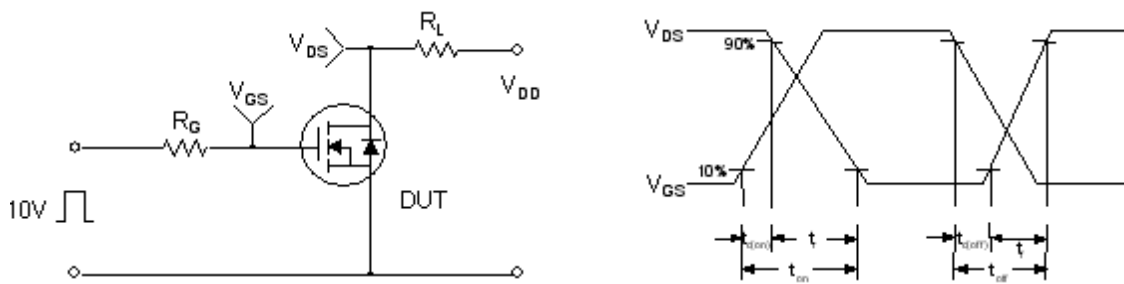


Figure 13. Resistive Switching Test Circuit & Waveforms

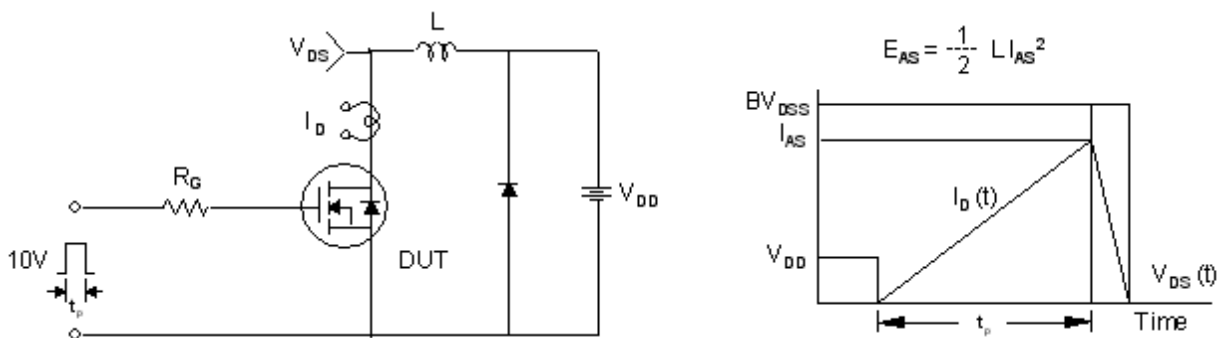


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

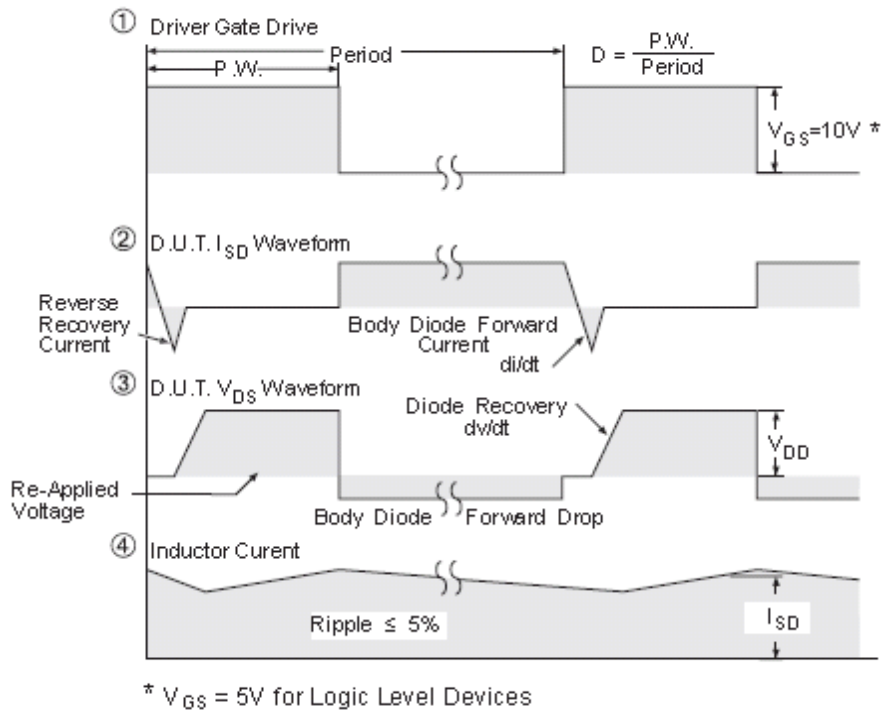
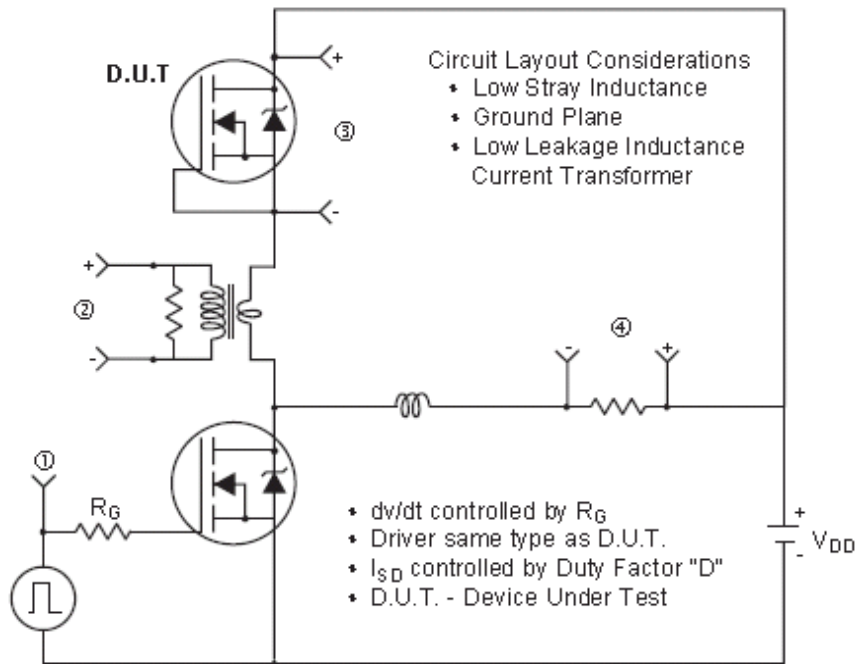


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms (For N-channel)

Disclaimers:

GOFORD has made reasonable commercial efforts to ensure that the information given in this data sheet is correct. However, it must clearly be understood that such information is for guidance only and does not constitute any representation or form part of any offer or contract.

For documents and material available from this data sheet, GOFORD does not warrant or assume any legal liability or responsibility for the accuracy, completeness, or usefulness of any information, product, technology or process disclosed hereunder.

GOFORD reserves the rights to at its own discretion to make any changes or improvements to this data sheet. Unless said data sheet is incorporated into the formal contract, any customer should not rely on the information as any specification or product parameters duly committed by GOFORD. Customers are hereby advised to verify that the information contained herein is current and complete before the entering of any contract or acknowledgement of any purchase order. Accordingly, all products specified hereunder shall be sold subject to GOFORD's terms and conditions supplied at the time of order acknowledgement. Except where agreed upon by contractual agreement, testing of all parameters of each product is not necessarily performed.

GOFORD does not warrant or convey any license either expressed or implied under its patent rights, nor the rights of others. Reproduction of information contained herein shall be only permissible if such reproduction is without any modification or alteration. Reproduction of this information with any alteration is an unfair and deceptive business practice. GOFORD is not responsible or liable for such altered documentation.

Resale of GOFORD's products with statements different from or beyond the parameters stated by GOFORD for that product or service voids all express or implied warranties for the associated GOFORD's product or service and is unfair and deceptive business practice. GOFORD is not responsible or liable for any such statements.

GOFORD's products are not authorized for use as critical components in life support devices or systems without the express written approval of GOFORD. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.